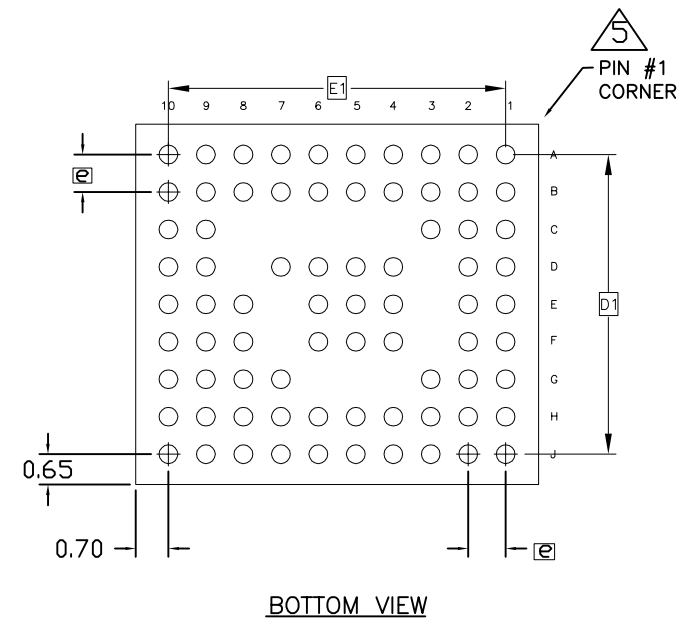
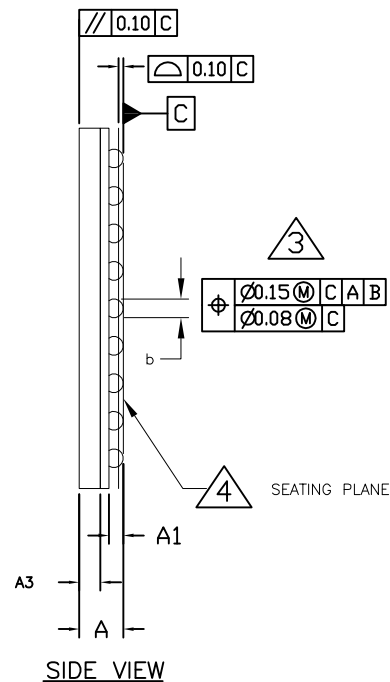
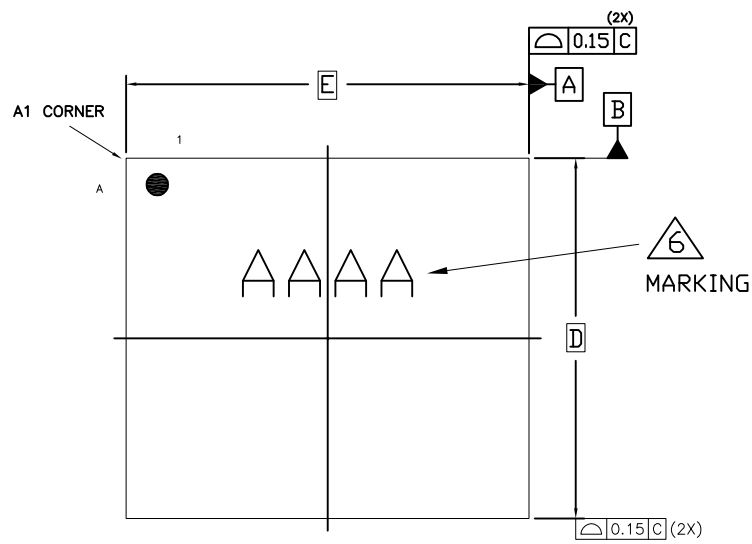




NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS
5. A1 BALL PAD CORNER I.D.
6. MARKING SHOWN IS FOR PKG. ORIENTATION ONLY

DIMENSIONS			
REF.	MIN.	NOM.	MAX.
A			1.04
A1	0.21	0.31	0.41
A3	0.45±0.05		
D	7.70 BSC		
D1	6.4 BSC		
E	8.60 BSC		
E1	7.20 BSC		
b	0.40±0.05		
e	0.80 BSC		
N	76		
PKG. CODE: X767A8F+1 X767A8F+2			



TITLE:
PACKAGE OUTLINE, 76 BALLS
FLIP CHIP CSP, 7.7×8.6×1.04 MM

APPROVAL
Ken Wang
03/05/2014

DOCUMENT CONTROL NO.
21-0733

REV. C 1/1

—DRAWING NOT TO SCALE—